AI in Chip Manufacturing

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Our company at a glance

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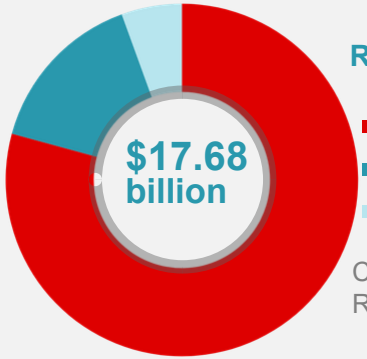
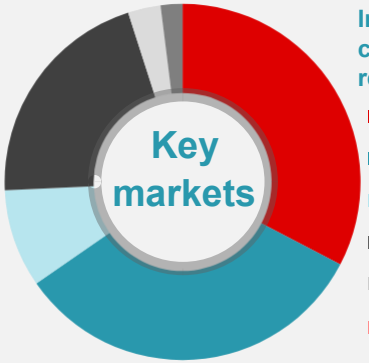


Revenue in 2025

- Analog: $14 billion
- Embedded: $2.7 billion
- Other: $979 million

Capital expenditures: $4.6 billion
Research & development: $2.1 billion



Industrial, automotive and data center combined comprised about 75% of TI's 2025 revenue

- Industrial: 33%
- Automotive: 33%
- Data center: 9%
- Personal electronics: 21%
- Communications equipment: 3%
- Other: 1%

Approximately 33K employees worldwide

~14K in the Americas

~2K in Europe

~18K in Asia-Pacific

80,000+ products for over 100,000 customers

15 manufacturing sites worldwide, tens of billions of chips produced each year

Easy and convenient product search, support and ordering, available 24/7

EcoVadis Silver Medal for Environmental Sustainability

Forbes Best Employers for New Graduates

Glassdoor's Best Places to Work 2025

Our presence in EMEA

Our presence across Europe

EMEA headquarters:
Freising, Germany

- Product Distribution Center
- Wafer Fab & EMEA headquarters
- Sales office locations
- R&D

Our production in EMEA

Since 1966 we have been producing semiconductors in Freising:

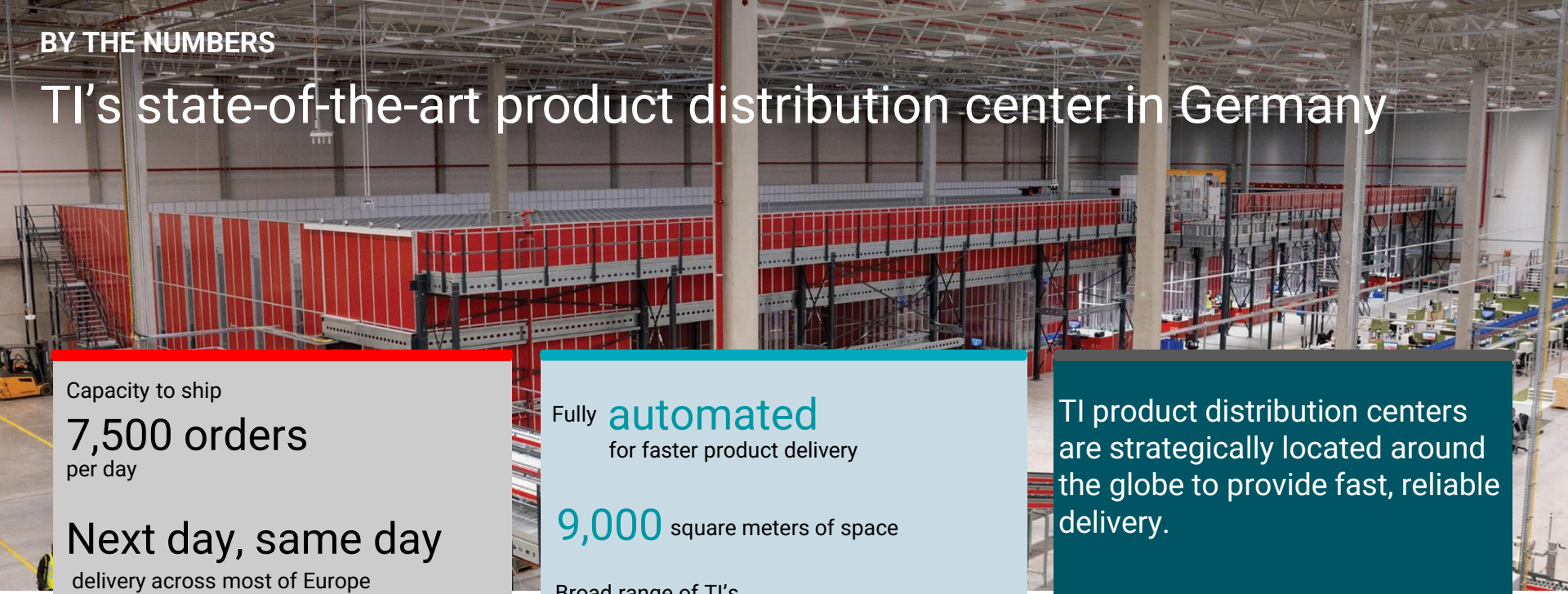
-Freising FAB is a 200-mm Analog FAB

-Space & automotive qualified

-Innovation Hub includes our Kilby Labs and a characterization lab

BY THE NUMBERS

TI’s state-of-the-art product distribution center in Germany



Capacity to ship

7,500 orders
per day

Next day, same day
delivery across most of Europe

Orders ready to ship in

15 minutes or less

Fully **automated**
for faster product delivery

9,000 square meters of space

Broad range of TI’s

analog and embedded
processing chips available

TI product distribution centers are strategically located around the globe to provide fast, reliable delivery.

Learn more:
TI.com/FrankfurtPDC

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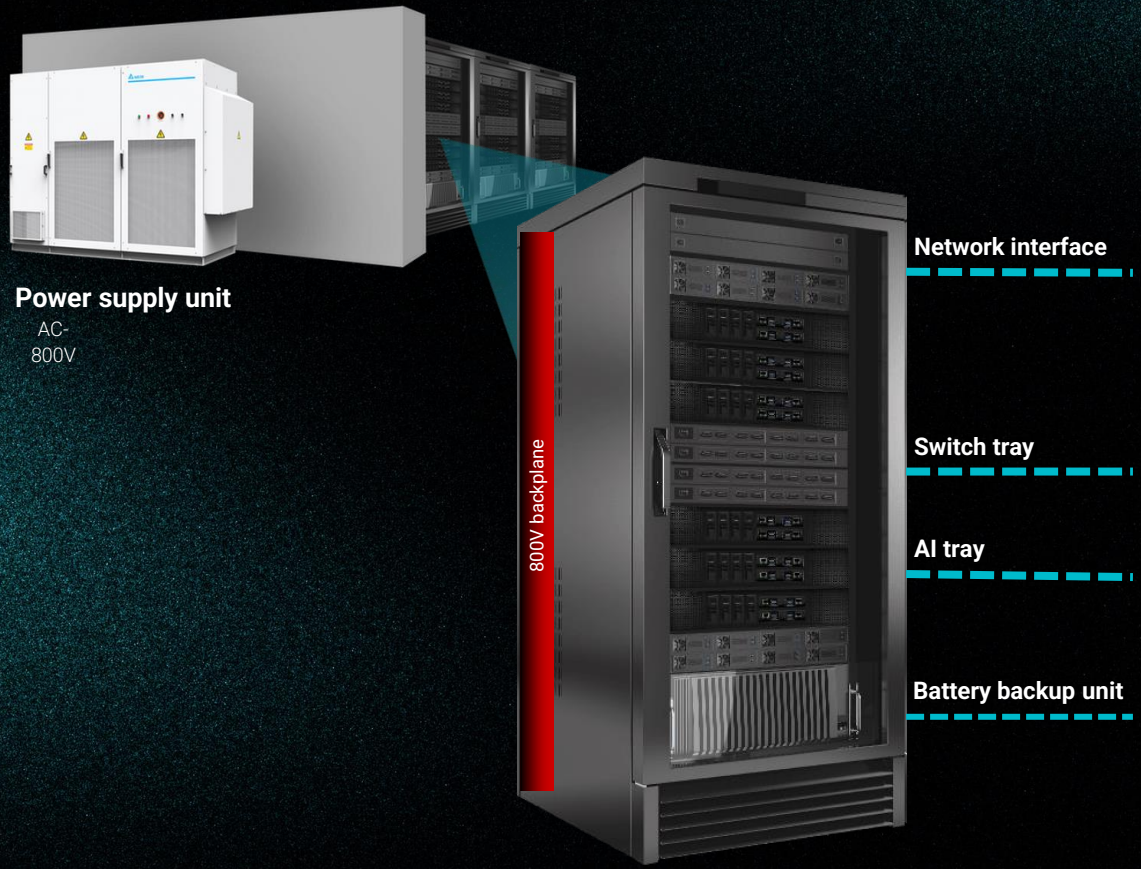
Data centers

Cloud computing, artificial intelligence and machine learning all demand more and faster computing.

The next generation of data centers require significantly more energy, networking and compute, which are fueled by semiconductors.

Next-gen rack architecture



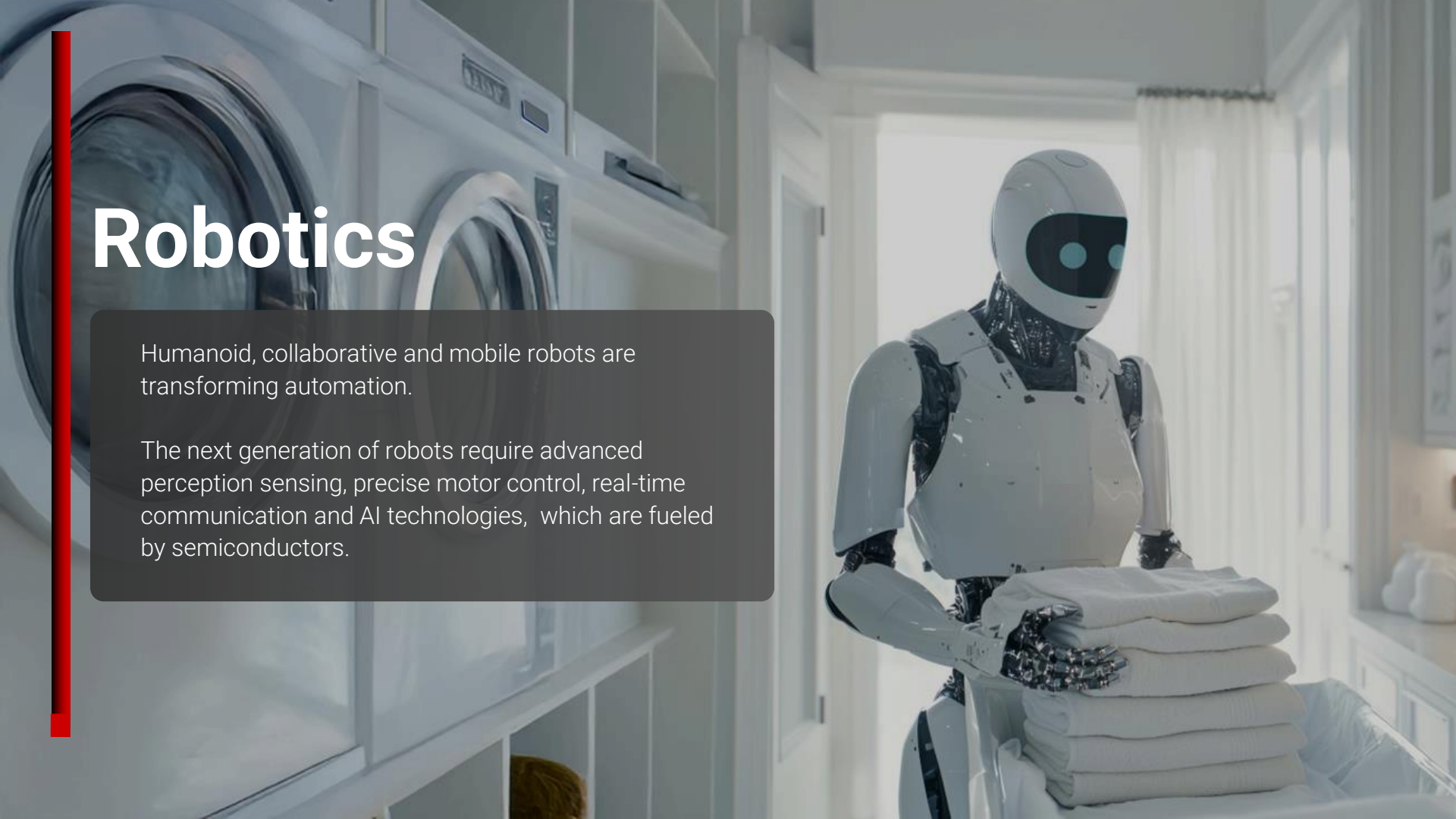
AI workloads are significantly more power hungry versus traditional compute needs.

TI technology positions us well to compete for all rack power opportunities from grid to gates.

Robotics

Humanoid, collaborative and mobile robots are transforming automation.

The next generation of robots require advanced perception sensing, precise motor control, real-time communication and AI technologies, which are fueled by semiconductors.



The evolution of robotics

Industrial robots

Collaborative robots

Mobile robots

Home service robots

Humanoid robots

Task-specific machines

Intelligent adaptive systems

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Humanoid anatomy

Perception sensing

Camera, lidar, mmWave radar, audio

System controller

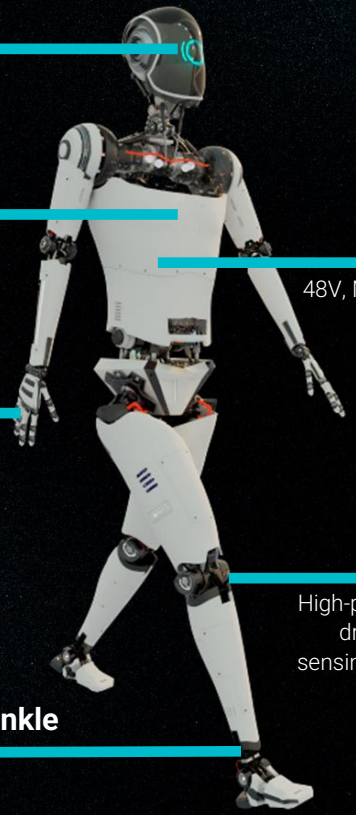
Graphics processing unit, CPU, Ethernet, CAN, FPD-Link

Hands

Low-power motors, microcontoller, motor drive, GaN, current & voltage sensing, tactile & torque sensor, Ethernet, EtherCat, CAN, encoder

Wrist, elbow, shoulders, neck, ankle

Mid-power motors, MCU, motor driver, GaN, current & voltage sensing, torque sensor, Ethernet, EtherCAT, CAN, encoder



Battery pack

48V, MCU, battery management system, battery charger, Ethernet, CAN

Hips, knee

High-power motors, MCU, motor drive, GaN, current & voltage sensing, torque sensor, Ethernet, EtherCat, CAN, encoder

As humanoids become smarter and more dexterous, they require more sophisticated systems.

TI technology positions us well to compete across sensing, processing and actuation technologies.

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Honoring 70 years, advancing for decades to come

70 years in Europe

est. 1956

Thank you.